

# Custom High Performance Cooling Solutions w/ maxiGRIP™ Attachment



ATS Part#: **ATS-59001-C1-R0**  
 Description: maxiGRIP™ HS Assembly, T766, BLACK-ANODIZED, 21MM COMP

Heat Sink Type: [maxiFLOW](#)  
 Heat Sink Attachment: [maxiGRIP](#)  
 Equivalent Part Number: [ATS-59001-C2-R0](#) **Discontinued**

*\*Image above is for illustration purpose only.*

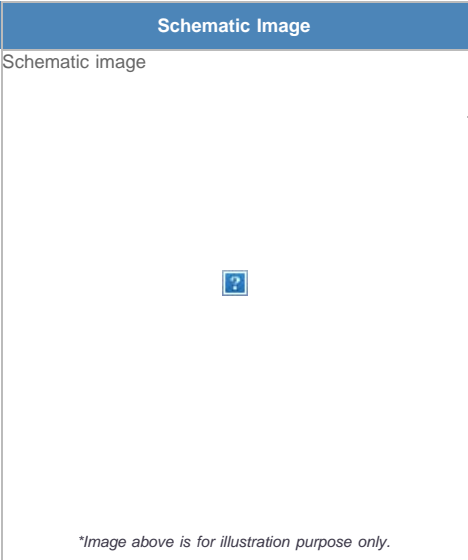
## Features & Benefits

- **maxiFLOW™** design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- **maxiGRIP™** attachment applies steady, even pressure to the component and does not require holes in the PCB
- Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards
- Comes pre-assembled with high performance, phase changing, thermal interface material
- Designed for flip-chip processors such as Freescale MPCs
- "Keep-Out" Requirements: An "Un-Populated" border zone of 5mm around the component is necessary to facilitate the Installation/Removal of the **maxiGRIP™**. Please refer to the **maxiGRIP™** Keep-Out Guidelines and **maxiGRIP™** Installation/Removal Instructions for further details.

## Thermal Performance

| AIR VELOCITY       |               | @200 LFM<br>1.0 M/S | @300 LFM<br>1.5 M/S | @400 LFM<br>2.0 M/S | @500 LFM<br>2.5 M/S | @600 LFM<br>3.0 M/S | @700 LFM<br>3.5 M/S | @800 LFM<br>4.0 M/S |
|--------------------|---------------|---------------------|---------------------|---------------------|---------------------|---------------------|---------------------|---------------------|
| THERMAL RESISTANCE | Unducted Flow | 4.50 °C/W           | 3.60 °C/W           | 3.20 °C/W           | 2.90 °C/W           | 2.70 °C/W           | 2.50 °C/W           | 2.40 °C/W           |
|                    | Ducted Flow   | 3.00                | n/a                 | n/a                 | n/a                 | n/a                 | n/a                 | n/a                 |

## Product Detail

| Schematic Image   | Dimension A | Dimension B | Dimension C | Dimension D | TIM  | Finish         |
|---|-------------|-------------|-------------|-------------|------|----------------|
|  <p><i>*Image above is for illustration purpose only.</i></p>  | 28.0 mm     | 45.0 mm     | 11.0 mm     | 59.0 mm     | T766 | BLACK-ANODIZED |
| <p><b>Notes:</b></p> <ul style="list-style-type: none"> <li>• Dimension <b>B</b> refers to component size</li> <li>• Dimension <b>C</b> is the heat sink height from the bottom of the base to the top of the fin field.</li> <li>• ATS-59001-C2-R0 is the exact heat sink assembly with an equivalent thermal interface material (Saint Gobain C1100F). NOTE: Saint Gobain C1100F is discontinued effective 12/31/10.</li> <li>• Thermal performance data are provided for reference only. Actual performance may vary by application.</li> <li>• ATS reserves the right to update or change its products without notice to improve the design or performance.</li> <li>• ATS certifies that this heat sink assembly is RoHS-6 and REACH compliant.</li> <li>• Contact ATS to learn about custom options available.</li> </ul> |             |             |             |             |      |                |

For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), [sales@qats.com](mailto:sales@qats.com) or [www.qats.com](http://www.qats.com).

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